

Features

- Very Low FOM $R_{DS(on)} \times Q_g$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 62.5°C/W Junction to Ambient
- Thermal Resistance: 1.5°C/W Junction to Case

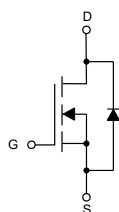
Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	650	V	
Gate-Source Voltage	V_{GS}	±30	V	
Continuous Drain Current	I_D	11	A	
Pulsed Drain Current (Note 2)	I_{DM}	45	A	
Single Pulse Avalanche Energy (Note 3)	E_{AS}	215	mJ	
Avalanche Current (Note 2)	I_{AR}	1.6	A	
Repetitive Avalanche Energy (Note 2)	E_{AR}	0.32	mJ	
Total Power Dissipation	$T_C=25^\circ\text{C}$	P_D	83.3	W

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

2. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

3. $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.

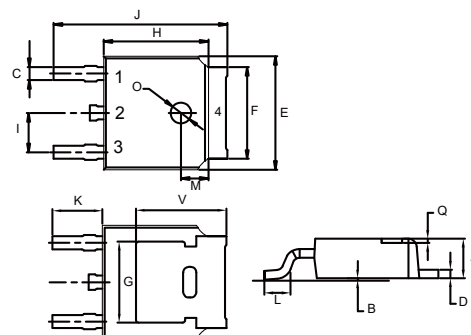
Internal Structure



1. Gate
2. Drain
3. Source

N-CHANNEL Super-Junction Power MOSFET

DPAK(TO-252)



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	0.087	0.094	2.20	2.40	
B	0.000	0.005	0.00	0.13	
C	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
E	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
H	0.236	0.244	6.00	6.20	
I	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.055	0.067	1.40	1.70	
M	0.063		1.60		TYP.
O	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.35		TYP.

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 30V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
		$V_{DS}=650V, V_{GS}=0V, T_J=150^\circ C$			100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
Drain-Source On-Resistance ^(Note 4)	$R_{DS(on)}$	$V_{GS}=10V, I_D=3.2A$		0.34	0.38	Ω
Forward transconductance ^(Note 4)	g_{FS}	$V_{DS}=10V, I_D=3.2A$		7.8		S
Dynamic Characteristics^(Note 5)						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		763		μF
Output Capacitance	C_{oss}			896		
Reverse Transfer Capacitance	C_{rss}			39		
Total Gate Charge	Q_g	$V_{DD}=520V, V_{GS}=10V, I_D=11A$		21		nC
Gate-Source Charge	Q_{gs}			5.3		
Gate-Drain Charge	Q_{gd}			7.5		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=325V, I_D=11A, R_G=25\Omega$		19		ns
Turn-On Rise Time	t_r			38		
Turn-Off Delay Time	$t_{d(off)}$			108		
Turn-Off Fall Time	t_f			36		
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C=25^\circ C$			11	A
Pulsed Diode Forward Current	I_{SM}				33	
Body Diode Voltage	V_{SD}	$I_{SD}=11A, V_{GS}=0V$			1.4	V
Reverse Recovery Time	t_{rr}	$V_R=520V, I_F=I_S, di_F/dt=100A/\mu s$		324		ns
Reverse Recovery Charge	Q_{rr}				3.8	μC
Peak Reverse Recovery Current	I_{rrm}				23	A

Note 4. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 1\%$.

5. Guaranteed by Design, Not Subject to Production Testing.

Curve Characteristics

Fig. 1 - Typical Output Characteristics

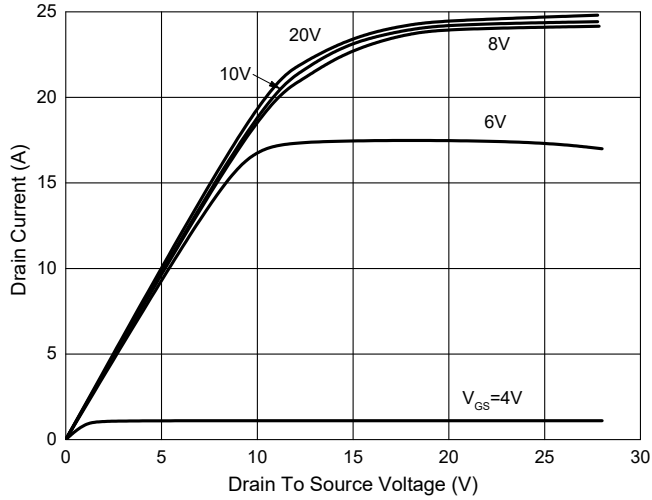


Fig. 2 - Transfer Characteristics

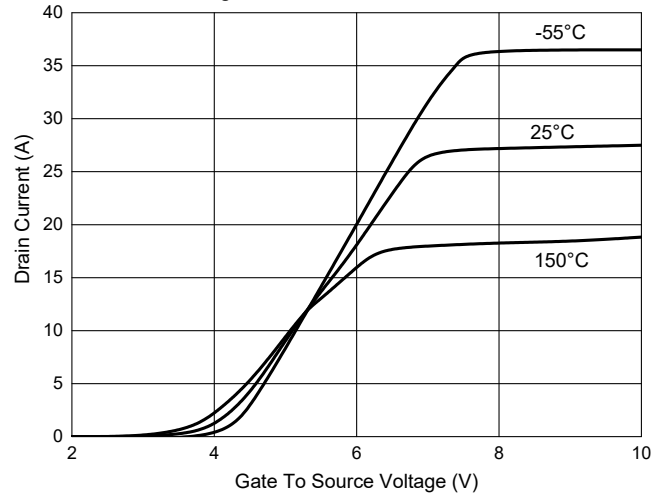


Fig. 3 - $R_{DS(ON)} - I_D$

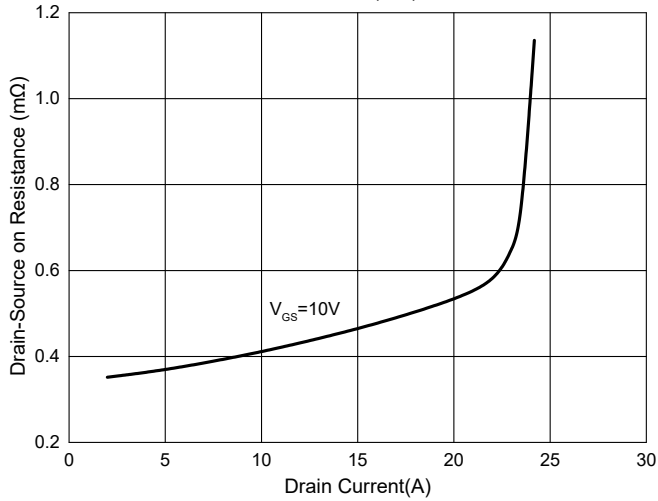


Fig. 4 - Normalized On Resistance Characteristics

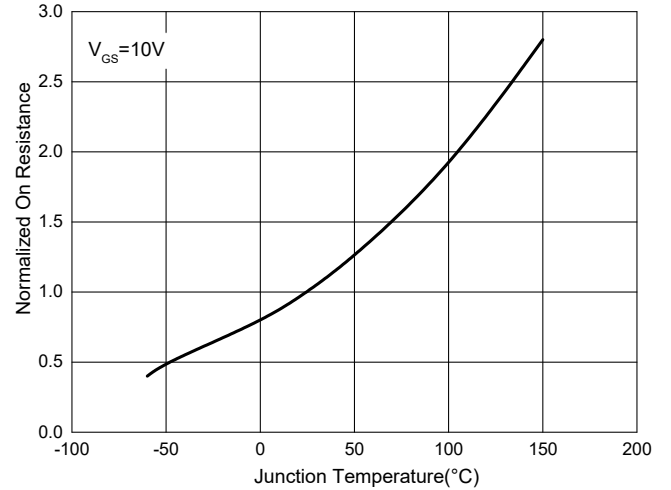


Fig. 5 - Gate Charge

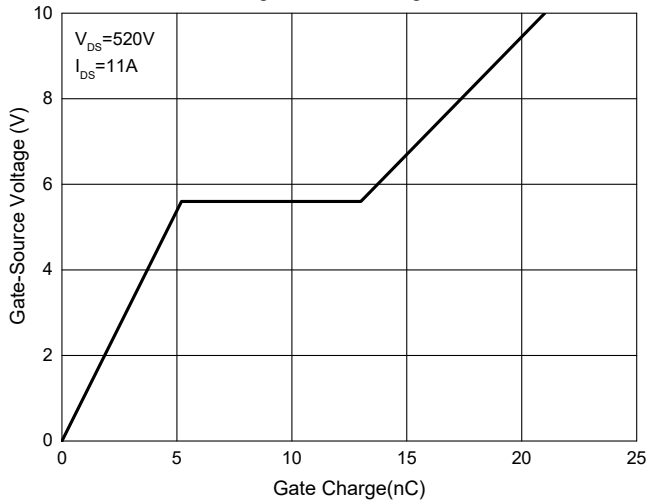


Fig. 6 - Capacitance Characteristics

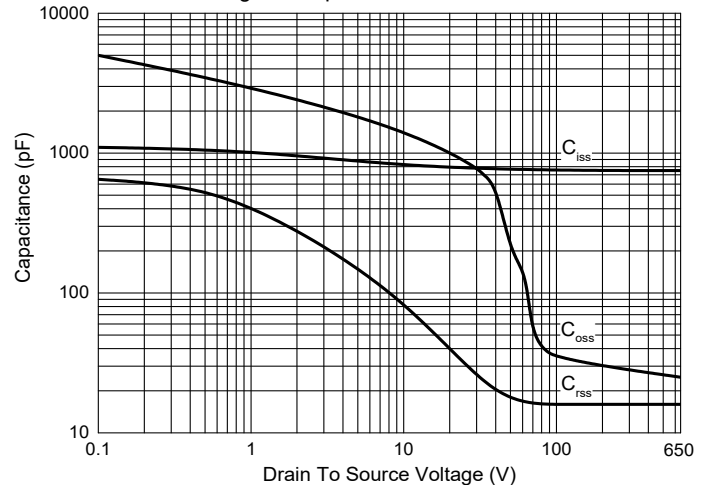


Fig. 7 - Normalized Drain-Source Breakdown Voltage

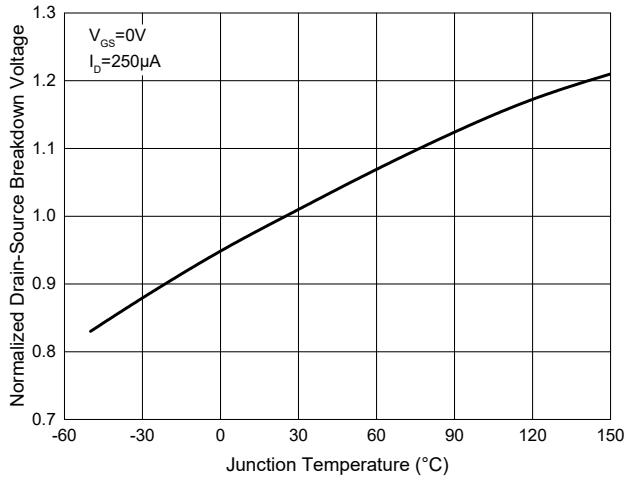


Fig. 8 - Safe Operation Area

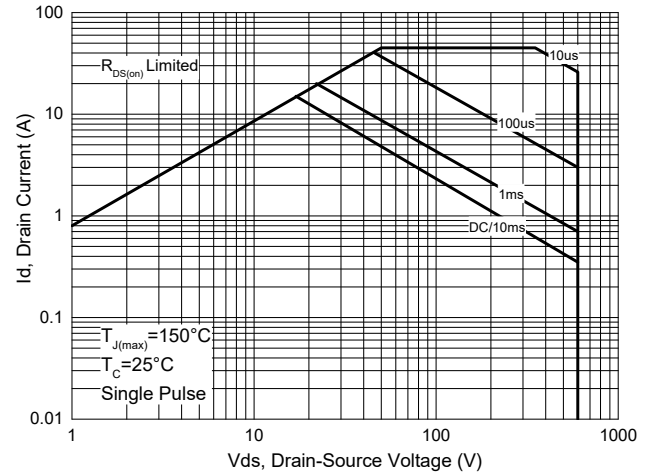
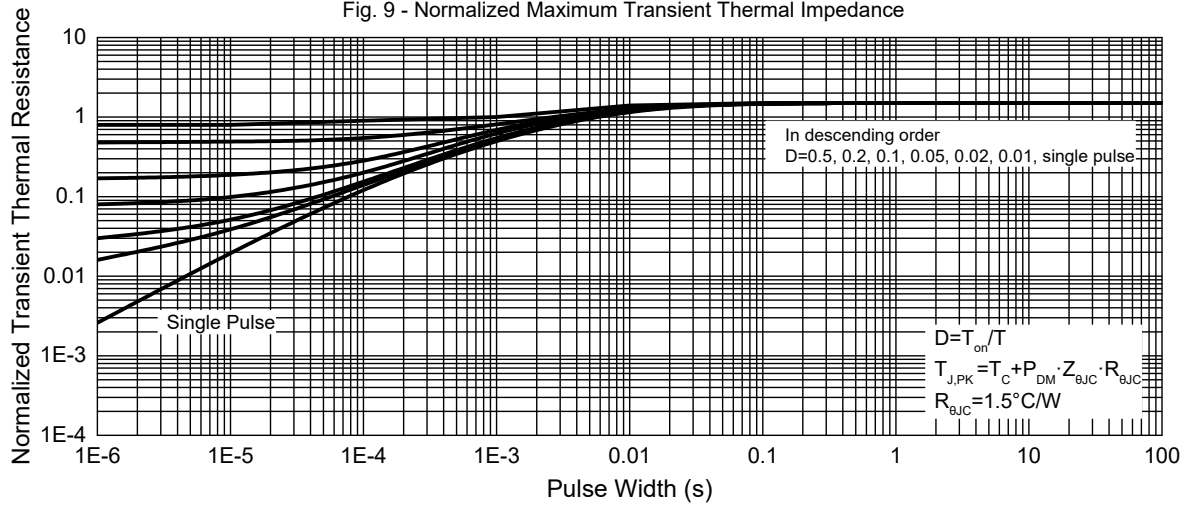


Fig. 9 - Normalized Maximum Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-BP	Tape&Reel: 2.5Kpcs/Reel

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